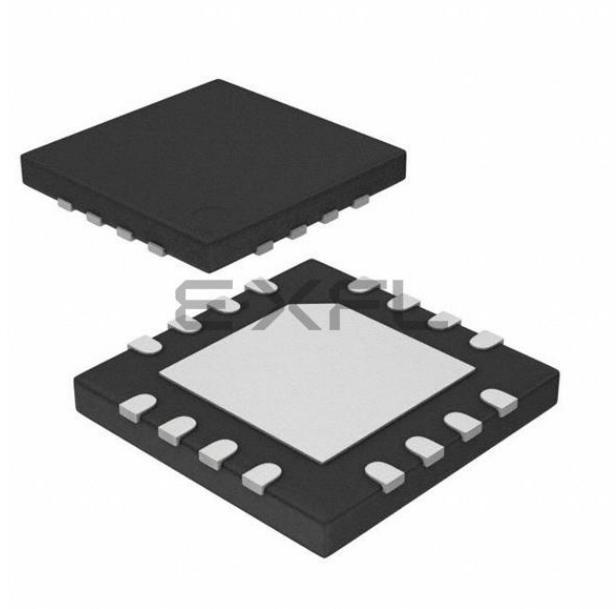

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	12
Program Memory Size	14KB (8K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 5.5V
Data Converters	A/D 11x10b; D/A 1x5b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	16-UQFN Exposed Pad
Supplier Device Package	16-UQFN (4x4)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f18325t-i-jq

4.4 Stack

All devices have a 16-level x 15-bit wide hardware stack (refer to Figure 4-4 through Figure 4-7). The stack space is not part of either program or data space. The PC is PUSHed onto the stack when CALL or CALLW instructions are executed or an interrupt causes a branch. The stack is POPed in the event of a RETURN, RETLW or a RETFIE instruction execution. PCLATH is not affected by a PUSH or POP operation.

The stack operates as a circular buffer and does not cause a Reset when either a Stack Overflow or Underflow occur if the STVREN bit is programmed to '0' (Configuration Words). This means that after the stack has been PUSHed sixteen times, the seventeenth PUSH overwrites the value that was stored from the first PUSH. The eighteenth PUSH overwrites the second PUSH (and so on). The STKOVF and STKUNF flag bits will be set on an Overflow/Underflow, regardless of whether the Reset is enabled.

If the STVREN bit in Configuration Words is programmed to '1', the device will be Reset if the stack is PUSHed beyond the sixteenth level or POPed beyond the first level, setting the appropriate bits (STKOVF or STKUNF, respectively) in the PCON register.

Note 1:	There are no instructions/mnemonics called PUSH or POP. These are actions that occur from the execution of the CALL, CALLW, RETURN, RETLW and RETFIE instructions or the vectoring to an interrupt address.

4.4.1 ACCESSING THE STACK

The stack is accessible through the TOSH, TOSL and STKPTR registers. STKPTR is the current value of the Stack Pointer. TOSH:TOSL register pair points to the TOP of the stack. Both registers are read/writable. TOS is split into TOSH and TOSL due to the 15-bit size of the PC. To access the stack, adjust the value of STKPTR, which will position TOSH:TOSL, then read/write to TOSH:TOSL. STKPTR is five bits to allow detection of overflow and underflow.

Note:	Care should be taken when modifying the STKPTR while interrupts are enabled.

During normal program operation, CALL, CALLW and Interrupts will increment STKPTR while RETLW, RETURN, and RETFIE will decrement STKPTR. At any time, STKPTR can be read to see how many levels remain available on the stack. The STKPTR always points at the currently used place on the stack. Therefore, a CALL or CALLW will increment the STKPTR and then write the PC, and a return will write the PC and then decrement the STKPTR.

Reference Figure 4-4 through Figure 4-7 for examples of accessing the stack.

REGISTER 5-3: CONFIGURATION WORD 3: MEMORY

R/P-1	U-1	U-1	U-1	U-1	U-1
LVP(1)	—	—	—	—	—
bit 13					bit 8

U-1	U-1	U-1	U-1	U-1	U-1	R/P-1	R/P-1
—	—	—	—	—	—	WRT1	WRT0
bit 7							bit 0

Legend:		
R = Readable bit	P = Programmable bit	U = Unimplemented bit, read as '1'
'0' = Bit is cleared	'1' = Bit is set	n = Value when blank or after Bulk Erase

bit 13 **LVP:** Low-Voltage Programming Enable bit(1)
- 1 = ON Low-Voltage Programming is enabled. $\overline{MCLR}$/VPP pin function is $\overline{MCLR}$. MCLRE Configuration bit is ignored.
- 0 = OFF HV on $\overline{MCLR}$/VPP must be used for programming.

bit 12-2 **Unimplemented:** Read as '1'

bit 1-0 **WRT<1:0>:** User NVM Self-Write Protection bits
- 11 = OFF Write protection off
- 10 = BOOT 0000h to 01FFh write-protected, 0200h to 1FFFh may be modified
- 01 = HALF 0000h to 0FFFh write-protected, 1000h to 1FFFh may be modified
- 00 = ALL 0000h to 1FFFh write-protected, no addresses may be modified

WRT applies only to the self-write feature of the device; writing through ICSP™ is never protected.

Note 1: The LVP bit cannot be programmed to '0' when Programming mode is entered via LVP.

REGISTER 7-4: OSCSTAT1: OSCILLATOR STATUS REGISTER 1

R-q/q	R-q/q	U-0	R-q/q	R-q/q	R-q/q	U-0	R-q/q
EXTOR	HFOR	—	LFOR	SOR	ADOR	—	PLLR
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	
q = Reset value is determined by hardware		

bit 7 **EXTOR:** EXTOSC (external) Oscillator Ready
- 1 = The oscillator is ready to be used
- 0 = The oscillator is not enabled, or is not yet ready to be used.

bit 6 **HFOR:** HFINTOSC Oscillator Ready
- 1 = The oscillator is ready to be used
- 0 = The oscillator is not enabled, or is not yet ready to be used.

bit 5 **Unimplemented:** Read as ‘0’

bit 4 **LFOR:** LFINTOSC Oscillator Ready
- 1 = The oscillator is ready to be used
- 0 = The oscillator is not enabled, or is not yet ready to be used.

bit 3 **SOR:** Secondary Oscillator Ready
- 1 = The oscillator is ready to be used
- 0 = The oscillator is not enabled, or is not yet ready to be used.

bit 2 **ADOR:** ADCRC Oscillator Ready
- 1 = The oscillator is ready to be used
- 0 = The oscillator is not enabled, or is not yet ready to be used

bit 1 **Unimplemented:** Read as ‘0’

bit 0 **PLLR:** PLL is ready
- 1 = The PLL is ready to be used
- 0 = The PLL is not enabled, the required input source is not ready, or the PLL is not ready.

REGISTER 7-5: OSCEN: OSCILLATOR MANUAL ENABLE REGISTER

R/W-0/0	R/W-0/0	U-0	R/W-0/0	R/W-0/0	R/W-0/0	U-0	U-0
EXTOEN	HFOEN	—	LFOEN	SOSCEN	ADOEN	—	—
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7 **EXTOEN:** External Oscillator Manual Request Enable bit
1 = EXTOSC is explicitly enabled, operating as specified by FEXTOSC
0 = EXTOSC could be enabled by another module

bit 6 **HFOEN:** HFINTOSC Oscillator Manual Request Enable bit
1 = HFINTOSC is explicitly enabled, operating as specified by OSCFRQ (Register 7-6)
0 = HFINTOSC could be enabled by another module

bit 5 **Unimplemented:** Read as ‘0’

bit 4 **LFOEN:** LFINTOSC (31 kHz) Oscillator Manual Request Enable bit
1 = LFINTOSC is explicitly enabled
0 = LFINTOSC could be enabled by another module

bit 3 **SOSCEN:** Secondary Oscillator Manual Request Enable bit
1 = Secondary Oscillator is explicitly enabled
0 = Secondary Oscillator could be enabled by another module

bit 2 **ADOEN:** ADOSC (600 kHz) Oscillator Manual Request Enable bit
1 = ADOSC is explicitly enabled
0 = ADOSC could be enabled by another module

bit 1 **Unimplemented:** Read as ‘0’

bit 0 **Unimplemented:** Read as ‘0’

TABLE 10-3: SUMMARY OF REGISTERS ASSOCIATED WITH WATCHDOG TIMER

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
STATUS	—	—	—	$\overline{TO}$	$\overline{PD}$	Z	DC	C	30
WDTCON	—	—	WDTPS<4:0>					SWDTEN	121

Legend: x = unknown, u = unchanged, – = unimplemented locations read as '0'. Shaded cells are not used by Watchdog Timer.

TABLE 10-4: SUMMARY OF CONFIGURATION WORD WITH WATCHDOG TIMER

Name	Bits	Bit -/7	Bit -/6	Bit 13/5	Bit 12/4	Bit 11/3	Bit 10/2	Bit 9/1	Bit 8/0	Register on Page
CONFIG2	13:8	—	—	$\overline{DEBUG}$	STVREN	PPS1WAY	—	BORV	—	65
	7:0	BOREN1	BOREN0	$\overline{LPBOREN}$	—	WDTE1	WDTE0	$\overline{PWRTE}$	MCLRE	

Legend: — = unimplemented location, read as '0'. Shaded cells are not used by Watchdog Timer.

REGISTER 11-6: NVMCON2: NONVOLATILE MEMORY CONTROL 2 REGISTER

W-0/0	W-0/0	W-0/0	W-0/0	W-0/0	W-0/0	W-0/0	W-0/0
NVMCON2							
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
S = Bit can only be set	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **NVMCON2<7:0>: Flash Memory Unlock Pattern bits**

To unlock writes, a 55h must be written first, followed by an AAh, before setting the WR bit of the NVMCON1 register. The value written to this register is used to unlock the writes.

TABLE 11-5: SUMMARY OF REGISTERS ASSOCIATED WITH NONVOLATILE MEMORY (NVM)

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
INTCON	GIE	PEIE	—	—	—	—	—	INTEDG	101
PIR2	TMR6IF	C2IF	C1IF	NVMIF	SSP2IF	BLC2IF	TMR4IF	NCO1IF	109
PIE2	TMR6IE	C2IE	C1IE	NVMIE	SSP2IE	BLC2IE	TMR4IE	NCO1IE	104
NVMCON1	—	NVMREGS	LWLO	FREE	WRERR	WREN	WR	RD	138
NVMCON2	NVMCON2								139
NVMADRL	NVMADR<7:0>								137
NVMADRH	—(1)	NVMADR<14:8>							137
NVMDATL	NVMDAT<7:0>								137
NVMDATH	—	—	NVMDAT<13:8>						137

Legend: — = unimplemented location, read as '0'. Shaded cells are not used by NVM.

Note 1: Unimplemented, read as '1'.

TABLE 11-6: SUMMARY OF CONFIGURATION WORD WITH NONVOLATILE MEMORY (NVM)

Name	Bits	Bit -/7	Bit -/6	Bit 13/5	Bit 12/4	Bit 11/3	Bit 10/2	Bit 9/1	Bit 8/0	Register on Page
CONFIG3	13:8	—	—	LVP	—	—	—	—	—	66
	7:0	—	—	—	—	—	—	WRT<1:0>		
CONFIG4	13:8	—	—	—	—	—	—	—	—	67
	7:0	—	—	—	—	—	—	$\overline{CPD}$	$\overline{CP}$	

Legend: — = unimplemented location, read as '0'. Shaded cells are not used by NVM.

22.3 ADC Acquisition Requirements

For the ADC to meet its specified accuracy, the charge holding capacitor (CHOLD) must be allowed to fully charge to the input channel voltage level. The Analog Input model is shown in Figure 22-4. The source impedance (RS) and the internal sampling switch (RSS) impedance directly affect the time required to charge the capacitor CHOLD. The sampling switch (RSS) impedance varies over the device voltage (VDD), refer to Figure 22-4. **The maximum recommended impedance for analog sources is 10 kΩ.** As the source impedance is decreased, the acquisition time may be decreased. After the analog input channel is selected (or changed), an ADC acquisition must be done before the conversion can be started. To calculate the minimum acquisition time, Equation 22-1 may be used. This equation assumes that 1/2 LSb error is used (1,024 steps for the ADC). The 1/2 LSb error is the maximum error allowed for the ADC to meet its specified resolution.

EQUATION 22-1: ACQUISITION TIME EXAMPLE

Assumptions: $Temperature = 50°C$ *and external impedance of* $10k\Omega$ *5.0V* V_{DD}

$$T_{ACQ} = \text{Amplifier Settling Time} + \text{Hold Capacitor Charging Time} + \text{Temperature Coefficient}$$
$$= T_{AMP} + T_C + T_{COFF}$$
$$= 2\mu s + T_C + [(Temperature - 25°C)(0.05\mu s/°C)]$$

The value for T_C *can be approximated with the following equations:*

$$V_{APPLIED}\left(1 - \frac{1}{(2^{n+1}) - 1}\right) = V_{CHOLD}$$;[1] V_{CHOLD} *charged to within 1/2 lsb*

$$V_{APPLIED}\left(1 - e^{\frac{-T_C}{RC}}\right) = V_{CHOLD}$$;[2] V_{CHOLD} *charge response to* $V_{APPLIED}$

$$V_{APPLIED}\left(1 - e^{\frac{-T_C}{RC}}\right) = V_{APPLIED}\left(1 - \frac{1}{(2^{n+1}) - 1}\right)$$;combining [1] and [2]

Note: Where n = number of bits of the ADC.

Solving for T_C*:*

$$T_C = -C_{HOLD}(R_{IC} + R_{SS} + R_S)\ ln(1/2047)$$
$$= -10pF(1k\Omega + 7k\Omega + 10k\Omega)\ ln(0.0004885)$$
$$= 1.37\mu s$$

Therefore:

$$T_{ACQ} = 2\mu s + 892ns + [(50°C - 25°C)(0.05\mu s/°C)]$$
$$= 4.62\mu s$$

Note 1: The reference voltage (VREF) has no effect on the equation, since it cancels itself out.

2: The charge holding capacitor (CHOLD) is not discharged after each conversion.

3: The maximum recommended impedance for analog sources is 10 kΩ. This is required to meet the pin leakage specification.

REGISTER 22-2: ADCON1: ADC CONTROL REGISTER 1

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	U-0	R/W-0/0	R/W-0/0	R/W-0/0
ADFM	ADCS<2:0>			—	ADNREF	ADPREF<1:0>	
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7 **ADFM:** ADC Result Format Select bit
1 = Right justified. Six Most Significant bits of ADRESH are set to '0' when the conversion result is loaded.
0 = Left justified. Six Least Significant bits of ADRESL are set to '0' when the conversion result is loaded.

bit 6-4 **ADCS<2:0>:** ADC Conversion Clock Select bits
111 = ADCRC (dedicated RC oscillator)
110 = FOSC/64
101 = FOSC/16
100 = FOSC/4
011 = ADCRC (dedicated RC oscillator)
010 = FOSC/32
001 = FOSC/8
000 = FOSC/2

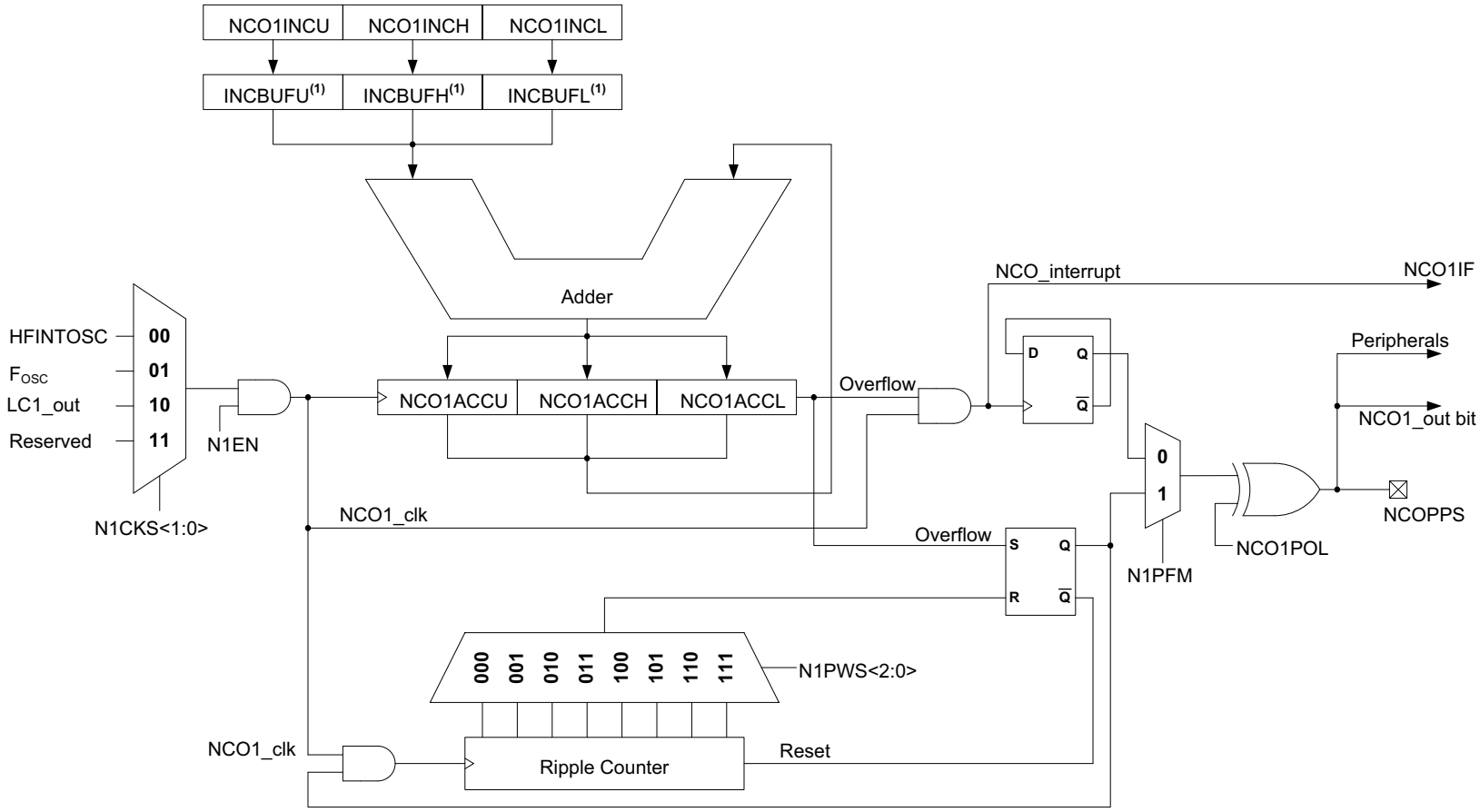
bit 3 **Unimplemented:** Read as '0'

bit 2 **ADNREF:** A/D Negative Voltage Reference Configuration bit
When ADON = 0, all multiplexer inputs are disconnected.
0 = VREF- is connected to VSS
1 = VREF- is connected to external VREF-

bit 1-0 **ADPREF<1:0>:** ADC Positive Voltage Reference Configuration bits
11 = VREF+ is connected to internal Fixed Voltage Reference (FVR) module(1)
10 = VREF+ is connected to external VREF+ pin(1)
01 = Reserved
00 = VREF+ is connected to VDD

Note 1: When selecting the VREF+ pin as the source of the positive reference, be aware that a minimum voltage specification exists. See Table 35-13 for details.

FIGURE 23-1: NUMERICALLY CONTROLLED OSCILLATOR MODULE SIMPLIFIED BLOCK DIAGRAM



Note 1: The increment registers are double-buffered to allow for value changes to be made without first disabling the NCO1 module. They are shown for reference only and are not user accessible.

REGISTER 23-2: NCO1CLK: NCO1 INPUT CLOCK CONTROL REGISTER

R/W-0/0	R/W-0/0	R/W-0/0	U-0	U-0	U-0	R/W-0/0	R/W-0/0
N1PWS<2:0>			—	—	—	N1CKS<1:0>	
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-5 **N1PWS<2:0>:** NCO1 Output Pulse Width Select(1, 2)
- 000 = NCO1 output is active for 1 input clock period
- 001 = NCO1 output is active for 2 input clock periods
- 010 = NCO1 output is active for 4 input clock periods
- 011 = NCO1 output is active for 8 input clock periods
- 100 = NCO1 output is active for 16 input clock periods
- 101 = NCO1 output is active for 32 input clock periods
- 110 = NCO1 output is active for 64 input clock periods
- 111 = NCO1 output is active for 128 input clock periods

bit 4-2 **Unimplemented:** Read as ‘0’

bit 1-0 **N1CKS<1:0>:** NCO1 Clock Source Select bits
- 00 = HFINTOSC (16 MHz)
- 01 = FOSC
- 10 = CLC1OUT
- 11 =Reserved

Note 1: N1PWS applies only when operating in Pulse Frequency mode.

2: If NCO1 pulse width is greater than NCO1 overflow period, the NCO1 output does not toggle.

REGISTER 23-3: NCO1ACCL: NCO1 ACCUMULATOR REGISTER – LOW BYTE

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
NCO1ACC<7:0>							
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-0 **NCO1ACC<7:0>:** NCO1 Accumulator, low byte

REGISTER 27-2: TxGCON(1): TIMERx GATE CONTROL REGISTER

R/W-0/u	R/W-0/u	R/W-0/u	R/W-0/u	R/W/HC-0/u	R-x/x	R/W-0/u	R/W-0/u
TMRxGE	TxGPOL	TxGTM	TxGSPM	TxGGO/$\overline{\text{DONE}}$	TxGVAL	TxGSS<1:0>	
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	HC = Bit is cleared by hardware

bit 7 **TMRxGE:** Timer1 Gate Enable bit

If TMRxON = 0:
This bit is ignored
If TMRxON = 1:
1 = Timerx counting is controlled by the Timer1 gate function
0 = Timerx is always counting

bit 6 **TxGPOL:** Timerx Gate Polarity bit

1 = Timerx gate is active-high (Timerx counts when gate is high)
0 = Timerx gate is active-low (Timerx counts when gate is low)

bit 5 **TxGTM:** Timerx Gate Toggle Mode bit

1 = Timerx Gate Toggle mode is enabled
0 = Timerx Gate Toggle mode is disabled and toggle flip-flop is cleared
Timerx gate flip-flop toggles on every rising edge.

bit 4 **TxGSPM:** Timerx Gate Single-Pulse Mode bit

1 = Timerx Gate Single-Pulse mode is enabled and is controlling Timerx gate
0 = Timerx Gate Single-Pulse mode is disabled

bit 3 **TxGGO/$\overline{\text{DONE}}$:** Timerx Gate Single-Pulse Acquisition Status bit

1 = Timerx gate single-pulse acquisition is ready, waiting for an edge
0 = Timerx gate single-pulse acquisition has completed or has not been started
This bit is automatically cleared when TxGSPM is cleared

bit 2 **TxGVAL:** Timerx Gate Value Status bit

Indicates the current state of the Timerx gate, latched at Q1, provided to TMRxH:TMRxL
Unaffected by Timerx Gate Enable (TMRxGE)

bit 1-0 **TxGSS<1:0>:** Timerx Gate Source Select bits

11 = Comparator 2 optionally synchronized output
10 = Comparator 1 optionally synchronized output
01 = Timer0 overflow output
00 = Timerx gate pin

Note 1: 'x' refers to either '1', '3' or '5' for the respective Timer1/3/5 registers.

29.2.2 TIMER1/3/5 MODE RESOURCE

Timer1/3/5 must be running in Timer mode or Synchronized Counter mode for the CCP module to use the capture feature. In Asynchronous Counter mode, the capture operation may not work.

See **Section 27.0 "Timer1/3/5 Module with Gate Control"** for more information on configuring Timer1/3/5.

Note:	Clocking Timer1/3/5 from the system clock (FOSC) should not be used in Capture mode. In order for Capture mode to recognize the trigger event on the CCPx pin, Timer1/3/5 must be clocked from the instruction clock (FOSC/4) or from an external clock source.

29.2.3 SOFTWARE INTERRUPT MODE

When the Capture mode is changed, a false capture interrupt may be generated. The user should keep the CCPxIE interrupt enable bit of the PIE4 register clear to avoid false interrupts. Additionally, the user should clear the CCPxIF interrupt flag bit of the PIR4 register following any change in Operating mode.

29.2.4 CCP PRESCALER

There are four prescaler settings specified by the CCPxMODE<3:0> bits of the CCPxCON register. Whenever the CCP module is turned off, or the CCP module is not in Capture mode, the prescaler counter is cleared. Any Reset will clear the prescaler counter.

Switching from one capture prescaler to another does not clear the prescaler and may generate a false interrupt. To avoid this unexpected operation, turn the module off by clearing the CCPxCON register before changing the prescaler. Example 29-1 demonstrates the code to perform this function.

EXAMPLE 29-1: CHANGING BETWEEN CAPTURE PRESCALERS

```
BANKSEL CCPxCON     ;Set Bank bits to point
                    ;to CCPxCON
CLRF    CCPxCON     ;Turn CCP module off
MOVLW   NEW_CAPT_PS ;Load the W reg with
                    ;the new prescaler
                    ;move value and CCP ON
MOVWF   CCPxCON     ;Load CCPxCON with this
                    ;value
```

29.2.5 CAPTURE DURING SLEEP

Capture mode depends upon the Timer1/3/5 module for proper operation. There are two options for driving the Timer1/3/5 module in Capture mode. It can be driven by the instruction clock (FOSC/4), or by an external clock source.

When Timer1/3/5 is clocked by FOSC/4, Timer1/3/5 will not increment during Sleep. When the device wakes from Sleep, Timer1/3/5 will continue from its previous state.

Capture mode will operate during Sleep when Timer1/3/5 is clocked by an external clock source.

30.5.3.3 7-bit Transmission with Address Hold Enabled

Setting the AHEN bit of the SSPxCON3 register enables additional clock stretching and interrupt generation after the eighth falling edge of a received matching address. Once a matching address has been clocked in, CKP is cleared and the SSPxIF interrupt is set.

Figure 30-19 displays a standard waveform of a 7-bit address slave transmission with AHEN enabled.

1. Bus starts Idle.
2. Master sends Start condition; the S bit of SSPxSTAT is set; SSPxIF is set if interrupt on Start detect is enabled.
3. Master sends matching address with R/$\overline{W}$ bit set. After the eighth falling edge of the SCL line the CKP bit is cleared and SSPxIF interrupt is generated.
4. Slave software clears SSPxIF.
5. Slave software reads ACKTIM bit of SSPxCON3 register, and R/$\overline{W}$ and D/$\overline{A}$ of the SSPxSTAT register to determine the source of the interrupt.
6. Slave reads the address value from the SSPxBUF register clearing the BF bit.
7. Slave software decides from this information if it wishes to $\overline{ACK}$ or not $\overline{ACK}$ and sets the ACKDT bit of the SSPxCON2 register accordingly.
8. Slave sets the CKP bit releasing SCL.
9. Master clocks in the $\overline{ACK}$ value from the slave.
10. Slave hardware automatically clears the CKP bit and sets SSPxIF after the $\overline{ACK}$ if the R/$\overline{W}$ bit is set.
11. Slave software clears SSPxIF.
12. Slave loads value to transmit to the master into SSPxBUF setting the BF bit.

Note: SSPxBUF cannot be loaded until after the $\overline{ACK}$.

13. Slave sets the CKP bit releasing the clock.
14. Master clocks out the data from the slave and sends an $\overline{ACK}$ value on the ninth SCL pulse.
15. Slave hardware copies the $\overline{ACK}$ value into the ACKSTAT bit of the SSPxCON2 register.
16. Steps 10-15 are repeated for each byte transmitted to the master from the slave.
17. If the master sends a not $\overline{ACK}$ the slave releases the bus allowing the master to send a Stop and end the communication.

Note: Master must send a not $\overline{ACK}$ on the last byte to ensure that the slave releases the SCL line to receive a Stop.

FIGURE 30-20: I²C SLAVE, 10-BIT ADDRESS, RECEPTION (SEN = 1, AHEN = 0, DHEN = 0)

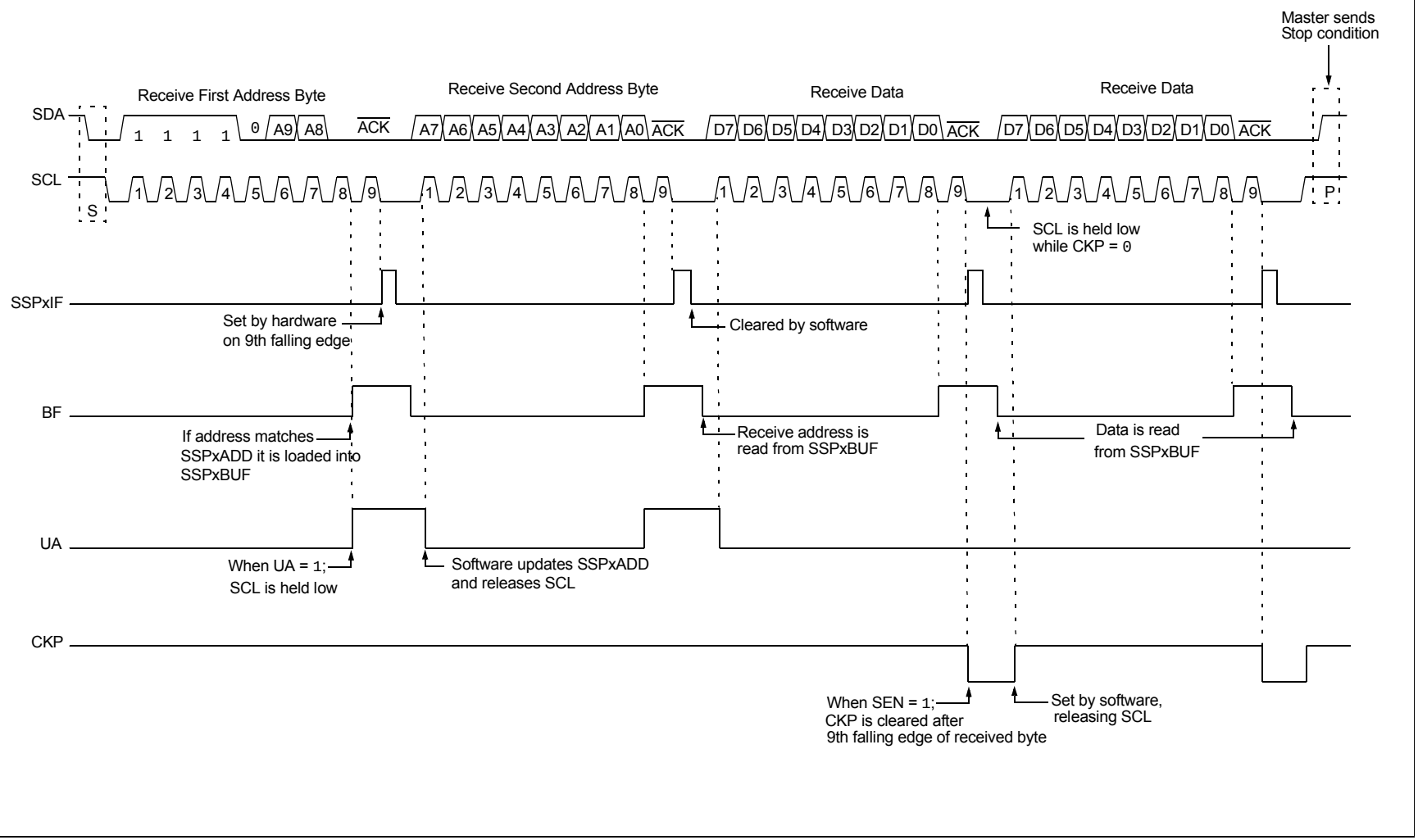


TABLE 34-3: PIC16(L)F18325/18345 INSTRUCTION SET (CONTINUED)

Mnemonic, Operands		Description	Cycles	14-bit Opcode MSb	LSb	Status Affected	Notes
INHERENT OPERATIONS							
CLRWDT	–	Clear Watchdog Timer	1	00 0000 0110 0100		$\overline{TO}$, $\overline{PD}$	
NOP	–	No Operation	1	00 0000 0000 0000			
RESET	–	Software device Reset	1	00 0000 0000 0001			
SLEEP	–	Go into Standby mode	1	00 0000 0110 0011		$\overline{TO}$, $\overline{PD}$	
TRIS	f	Load TRIS register with W	1	00 0000 0110 0fff			
C-COMPILER OPTIMIZED							
ADDFSR	n, k	Add Literal k to FSRn	1	11 0001 0nkk kkkk			
MOVIW	n mm	Move Indirect FSRn to W with pre/post inc/dec modifier, mm	1	00 0000 0001 0nmm		Z	**2, 3**
	k[n]	Move INDFn to W, Indexed Indirect.	1	11 1111 0nkk kkkk		Z	**2**
MOVWI	n mm	Move W to Indirect FSRn with pre/post inc/dec modifier, mm	1	00 0000 0001 1nmm			**2, 3**
	k[n]	Move W to INDFn, Indexed Indirect.	1	11 1111 1nkk kkkk			**2**

Note 1: If the Program Counter (PC) is modified, or a conditional test is true, the instruction requires two cycles. The second cycle is executed as a NOP.

2: If this instruction addresses an INDF register and the MSb of the corresponding FSR is set, this instruction will require one additional instruction cycle.

3: See **Section 34.2 "Instruction Descriptions"** for detailed MOVIW and MOVWI instruction descriptions.

35.2 Standard Operating Conditions

The standard operating conditions for any device are defined as:

Operating Voltage: $V_{DDMIN} \leq V_{DD} \leq V_{DDMAX}$
Operating Temperature: $T_{A\_MIN} \leq T_A \leq T_{A\_MAX}$

V_{DD} — Operating Supply Voltage(1)

PIC16LF18325/18345

- V_{DDMIN} (Fosc ≤ 16 MHz) ..... +1.8V
- V_{DDMIN} (Fosc ≤ 32 MHz) ..... +2.5V
- V_{DDMAX} ..... +3.6V

PIC16F18325/18345

- V_{DDMIN} (Fosc ≤ 16 MHz) ..... +2.3V
- V_{DDMIN} (Fosc ≤ 32 MHz) ..... +2.5V
- V_{DDMAX} ..... +5.5V

T_A — Operating Ambient Temperature Range

Industrial Temperature

- T_{A_MIN} ..... -40°C
- T_{A_MAX} ..... +85°C

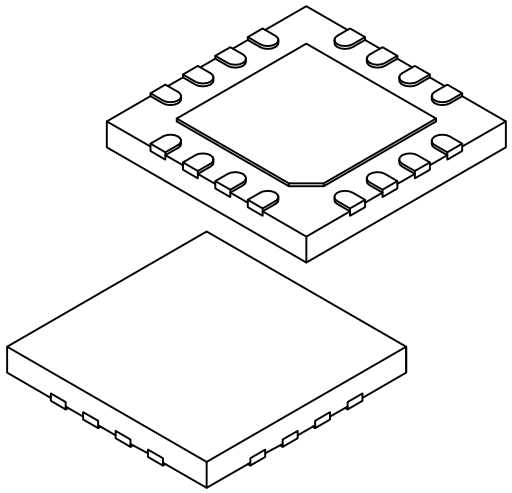
Extended Temperature

- T_{A_MIN} ..... -40°C
- T_{A_MAX} ..... +125°C

Note 1: See Parameter D002, DC Characteristics: Supply Voltage.

16-Lead Ultra Thin Plastic Quad Flat, No Lead Package (JQ) - 4x4x0.5 mm Body [UQFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		16	
Pitch	e		0.65 BSC	
Overall Height	A	0.45	0.50	0.55
Standoff	A1	0.00	0.02	0.05
Terminal Thickness	A3		0.127 REF	
Overall Width	E		4.00 BSC	
Exposed Pad Width	E2	2.50	2.60	2.70
Overall Length	D		4.00 BSC	
Exposed Pad Length	D2	2.50	2.60	2.70
Terminal Width	b	0.25	0.30	0.35
Terminal Length	L	0.30	0.40	0.50
Terminal-to-Exposed-Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated
3. Dimensioning and tolerancing per ASME Y14.5M

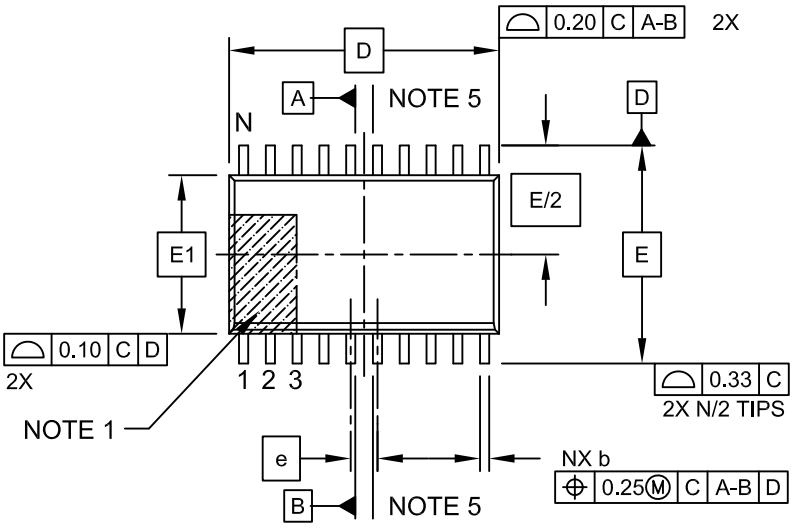
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

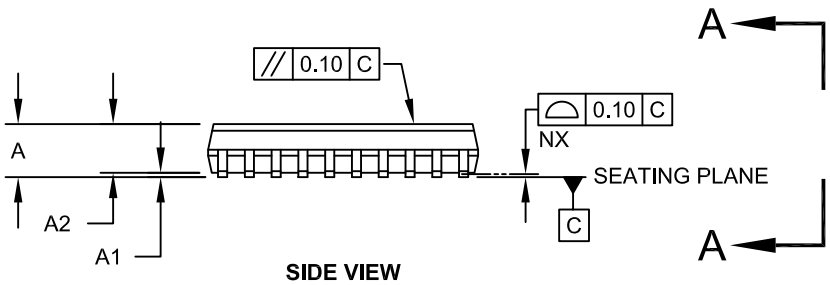
Microchip Technology Drawing C04-257A Sheet 2 of 2

20-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

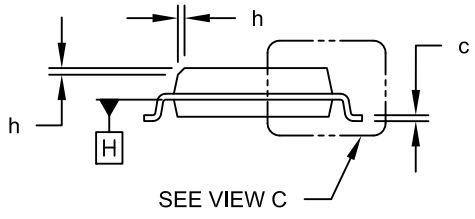
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



TOP VIEW



SIDE VIEW

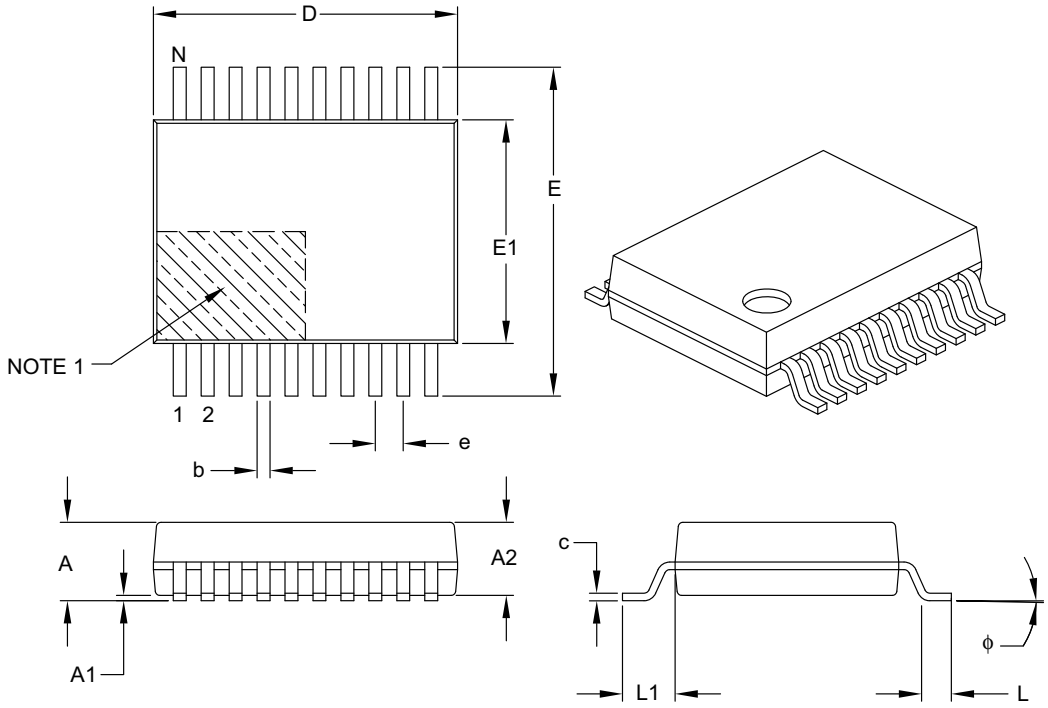


VIEW A-A

Microchip Technology Drawing C04-094C Sheet 1 of 2

20-Lead Plastic Shrink Small Outline (SS) – 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		20	
Pitch	e		0.65 BSC	
Overall Height	A	–	–	2.00
Molded Package Thickness	A2	1.65	1.75	1.85
Standoff	A1	0.05	–	–
Overall Width	E	7.40	7.80	8.20
Molded Package Width	E1	5.00	5.30	5.60
Overall Length	D	6.90	7.20	7.50
Foot Length	L	0.55	0.75	0.95
Footprint	L1		1.25 REF	
Lead Thickness	c	0.09	–	0.25
Foot Angle	ϕ	0°	4°	8°
Lead Width	b	0.22	–	0.38

Notes:

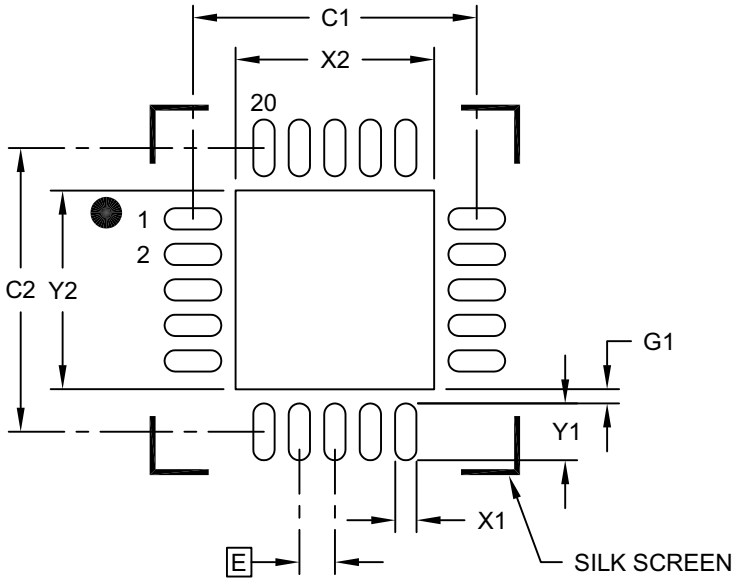
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.20 mm per side.
3. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-072B

20-Lead Ultra Thin Plastic Quad Flat, No Lead Package (GZ) - 4x4x0.5 mm Body [UQFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.50 BSC	
Optional Center Pad Width	X2			2.80
Optional Center Pad Length	Y2			2.80
Contact Pad Spacing	C1		4.00	
Contact Pad Spacing	C2		4.00	
Contact Pad Width (X20)	X1			0.30
Contact Pad Length (X20)	Y1			0.80
Contact Pad to Center Pad (X20)	G1	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-2255A

